Technical Data Sheet

LOCTITE ABLESTIK ABP 8037TI

January 2016

PRODUCT DESCRIPTION

LOCTITE ABLESTIK ABP 8037TI provides the following product characteristics:

Technology	Acrylate
Appearance	Silver paste
Filler Type	Silver
Filler Weight, %	82
Cure	Heat cure
Product Benefits	• Excellent electrical conductivity • High thermal conductivity • Excellent adhesive strength • Stable at high temperatures • Hydrophobic
Application	Die attach
Key Substrates	• Wide variety of metals and ceramic surfaces • Silver Plated Copper • Preplated leadframes (NiPdAu)

LOCTITE ABLESTIK ABP 8037TI silver filled conductive adhesive is recommended for use in the attachment of integrated circuits and components onto metal leadframes and advanced substrates.

TYPICAL PROPERTIES OF UNCURED MATERIAL

Thixotropic Index (0.5/5 rpm)	5.8
Viscosity, Brookfield - HA, 25 °C, mPa·s (cP):	
Spindle 51, speed 5 rpm	11,000
Work Life @ 25°C, hours	24
Shelf Life @ -40°C (from date of manufacture), days	365

TYPICAL CURING PERFORMANCE

Cure Schedule

30 minute ramp to 175ºC, hold 30 minutes @ 175 °C

Alternate Cure Schedule

30 minute ramp to 150ºC, hold 30 minutes @ 150 °C

This material can also be cured at a lower temperature for the same cure time.

The above cure profiles are guideline recommendations. Cure conditions (time and temperature) may vary based on customers' experience and their application requirements, as well as customer curing equipment, oven loading and actual oven temperatures.

TYPICAL PROPERTIES OF CURED MATERIAL

Physical Properties

Coefficient of Thermal Expansion :	
Below Tg, ppm/°C	62
Above Tg, ppm/°C	94
Glass Transition Temperature (Tg) by TMA, °C	46
Thermal Conductivity, W/(m-K)	4.1

Young's modulus (E) :

@ -65°C	N/mm²	8,400
	(psi)	(1,218,317)
@ 25°C	N/mm²	5,900
	(psi)	(855,722)
@ 100°C	N/mm²	4,100
	(psi)	(594,654)
@ 150°C	N/mm²	2,900
	(psi)	(420,609)
@ 200°C	N/mm²	1,600
	(psi)	(232,060)
@ 250°C	N/mm²	1,300
	(psi)	(188,549)
@ 300°C	N/mm²	1,700
	(psi)	(246,564)

Extractable Ionic Content, , ppm:	
Chloride (Cl-)	10
Sodium (Na+)	20
Potassium (K+)	1

Electrical Properties

Volume Resistivity, ohms-cm	6.00×10^{-5}

TYPICAL PERFORMANCE OF CURED MATERIAL

Sample cured 30 minute ramp to 150ºC, hold 30 minutes @ 150 °C.

Miscellaneous

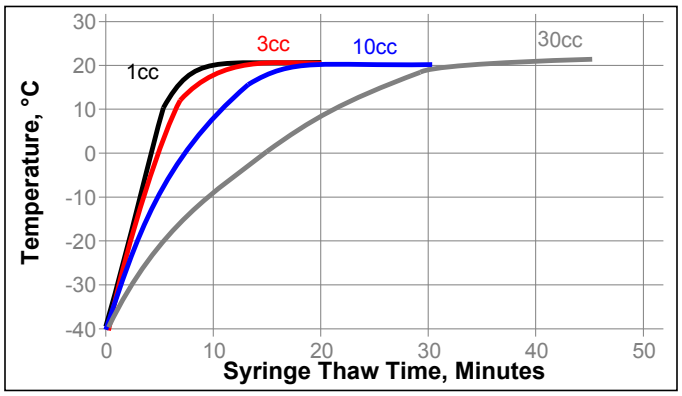
Die Shear Strength:	
120 x 120 mil Ag/Cu LF, Kg:	
@ 25°C	17.6
@ 270°C	7.4
120 x 120 mil Si die on PPF LF, Kg:	
@ 25°C	17.5
@ 270°C	6.9

GENERAL INFORMATION

For safe handling information on this product, consult the Material Safety Data Sheet, (MSDS).

THAWING:

1. Allow container to reach room temperature before use.
2. After removing from the freezer, set the syringes to stand vertically while thawing.
3. Refer to the Syringe Thaw time chart for the thaw time recommendation.
4. DO NOT open the container before contents reach 25°C temperature. Any moisture that collects on the thawed container should be removed prior to opening the container.
5. DO NOT re-freeze. Once thawed to 25°C, the adhesive should not be re-frozen.



DIRECTIONS FOR USE

1. Thawed adhesive should immediately be placed on dispense equipment for use.
2. If the adhesive is transferred to a final dispensing reservoir, care must be exercised to avoid entrapment of contaminants and/or air into the adhesive.
3. Adhesive must be completely used within the products recommended work life.
4. Silver-resin separation may occur if the adhesive is left out at room temperature, beyond the recommended work life.
5. Apply enough adhesive to achieve a 25 to 50 µm wet bondline thickness, dispensed with approximately 25 to 50 % filleting on all sides of the die.
6. Alternate dispense amounts may be used depending on the application requirements.
7. Star or crossed shaped dispense patterns will yield fewer bondline voids than the matrix style of dispense pattern.

Not for product specifications

The technical data contained herein are intended as reference only. Please contact your local quality department for assistance and recommendations on specifications for this product.

Storage

Store product in the unopened container in a dry location. Storage information may be indicated on the product container labeling.

Optimal Storage: -40 °C. Storage below minus (-)40 °C or greater than minus (-)40 °C can adversely affect product properties.

Material removed from containers may be contaminated during use. Do not return product to the original container. Henkel Corporation cannot assume responsibility for product which has been contaminated or stored under conditions other than those previously indicated. If additional information is required, please contact your local Technical Service Center or Customer Service Representative.

Conversions

(°C x 1.8) + 32 = °F
kV/mm x 25.4 = V/mil
mm / 25.4 = inches
N x 0.225 = lb
N/mm x 5.71 = lb/in
psi x 145 = N/mm²
MPa = N/mm²
N·m x 8.851 = lb·in
N·m x 0.738 = lb·ft
N·mm x 0.142 = oz·in
mPa·s = cP

Disclaimer

Note:

The information provided in this Technical Data Sheet (TDS) including the recommendations for use and application of the product are based on our knowledge and experience of the product as at the date of this TDS. The product can have a variety of different applications as well as differing application and working conditions in your environment that are beyond our control. Henkel is, therefore, not liable for the suitability of our product for the production processes and conditions in respect of which you use them, as well as the intended applications and results. We strongly recommend that you carry out your own prior trials to confirm such suitability of our product.
Any liability in respect of the information in the Technical Data Sheet or any other written or oral recommendation(s) regarding the concerned product is excluded, except if otherwise explicitly agreed and except in relation to death or personal injury caused by our negligence and any liability under any applicable mandatory product liability law.

In case products are delivered by Henkel Belgium NV, Henkel Electronic Materials NV, Henkel Nederland BV, Henkel Technologies France SAS and Henkel France SA please additionally note the following:
In case Henkel would be nevertheless held liable, on whatever legal ground, Henkel's liability will in no event exceed the amount of the concerned delivery.

In case products are delivered by Henkel Colombiana, S.A.S. the following disclaimer is applicable:
The information provided in this Technical Data Sheet (TDS) including the recommendations for use and application of the product are based on our knowledge and experience of the product as at the date of this TDS. Henkel is, therefore, not liable for the suitability of our product for the production processes and conditions in respect of which you use them, as well as the intended applications and results. We strongly recommend that you carry out your own prior trials to confirm such suitability of our product.
Any liability in respect of the information in the Technical Data Sheet or any other written or oral recommendation(s) regarding the concerned product is excluded, except if otherwise explicitly agreed and except in relation to death or personal injury caused by our negligence and any liability under any applicable mandatory product liability law.

In case products are delivered by Henkel Corporation, Resin Technology Group, Inc., or Henkel Canada Corporation, the following disclaimer is applicable:
The data contained herein are furnished for information only and are believed to be reliable. We cannot assume responsibility for the results obtained by others over whose methods we have no control. It is the user's responsibility to determine suitability for the user's purpose of any production methods mentioned herein and to adopt such precautions as may be advisable for the protection of property and of persons against any hazards that may be involved in the handling and use thereof. In light of the foregoing, **Henkel Corporation specifically disclaims all warranties expressed or implied, including warranties of merchantability or fitness for a particular purpose, arising from sale or use of Henkel Corporation's products. Henkel Corporation specifically disclaims any liability for consequential or incidental damages of any kind, including lost profits.** The discussion herein of various processes or compositions is not to be interpreted as representation that they are free from domination of patents owned by others or as a license under any Henkel Corporation patents that may cover such processes or compositions. We recommend that each prospective user test his proposed application before repetitive use, using this data as a guide. This product may be covered by one or more United States or foreign patents or patent applications.

Trademark usage

Except as otherwise noted, all trademarks in this document are trademarks of Henkel Corporation in the U.S. and elsewhere. ® denotes a trademark registered in the U.S. Patent and Trademark Office.

Reference 0.0

This document was created and digitally signed by tdx.henkel.com at 2025-11-28T09:30:23.334Z